

Filename: PMP5540REVB_bom.xls						
Date: 07/13/2010						
PMP5540REVB BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	330pF	Capacitor, Ceramic, 50V, [temp], [tol]	0603	std	std
1	C100	1nF	Capacitor, Ceramic, Low Inductance, 50V, X7R	0603	Std	Std
2	C13, C27	100uF	Capacitor, Aluminum, 16V, ±20%	0.260 x 0.276 inch	EEEFK1C101P	Panasonic
1	C2	0.22uF	Capacitor, Ceramic, 16V, [temp], [tol]	0603	std	std
1	C3	2.2nF	Capacitor, Ceramic, 50V, X7R	0603	std	std
1	C4	8.2nF	Capacitor, Ceramic, 50V, [temp], [tol]	0603	std	std
2	C5, C7	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	std	std
6	C8, C10, C11, C12, C15, C28	22uF	Capacitor, Ceramic, 16V, X7R, 15%	1210	C3225X7R1C226M	TDK
1	C9	100pF	Capacitor, Ceramic, vvV, [temp], [tol]	0603	std	std
1	D1	MBRS540	Diode, 5A, 40V	SMC	MBRS540	ONsemi
2	D99, D100	ZHCS1006	Diode, Schottky, 1000-mA, 60-V	SOT-23	ZHCS1006	Zetex
2	J1, J2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
1	L2	10uH	Inductor, SMT, 2.67Arms, 76milliohm	0.492 x 0.492 inch	DRQ125-100-R	Cooper
1	Q1	CSD16411Q3	MOSFET, NChan, 25V, 14A, 12 milliohm	QFN3.3x3.3 mm	CSD16411Q3	TI
1	R1	182k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R10	1k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R100	0.06	Resistor, Chip, 1/4 watt, ± 5%	1206	Std	Std
1	R11	0.03	Resistor, Chip, 1/2W, 1%	1812	Std	Std
1	R2	6.49k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R3	2.0k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R5	12.4k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R7	10	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R9	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std
3	TP1, TP8, TP11	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
2	TP2, TP10	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
2	TP4, TP5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TPS40210DGS	IC, Low Cost Non-Synchronous Boost Controller	DGS10	TPS40210DGS	TI
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants.					
	Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk (***) cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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